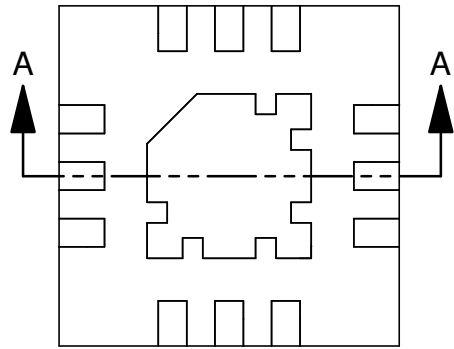
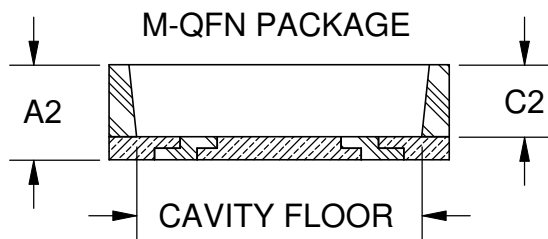
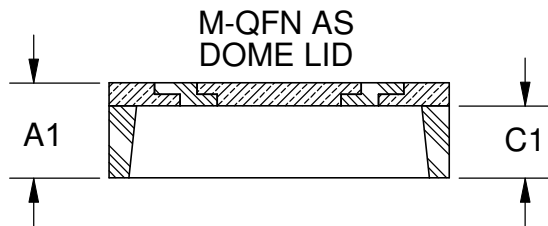


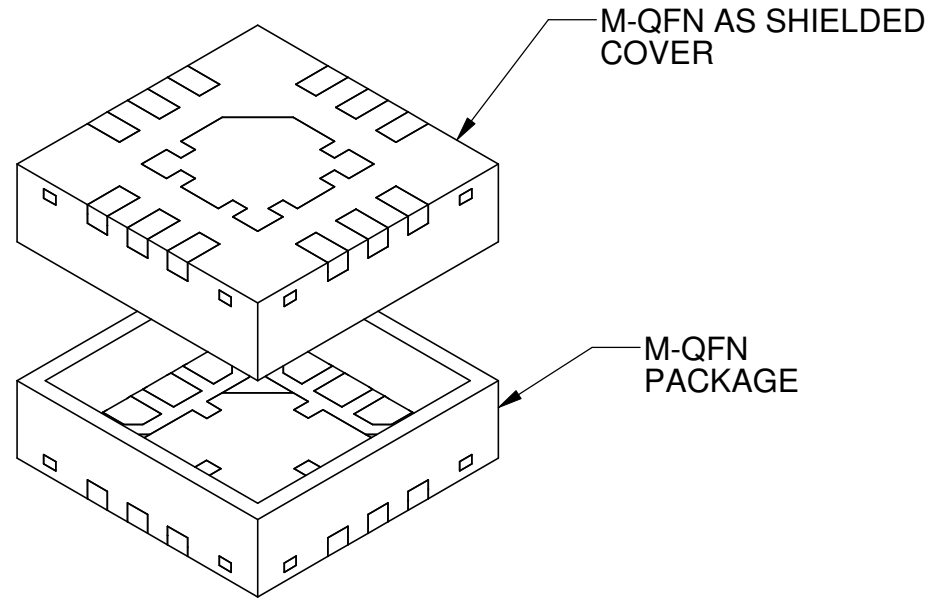
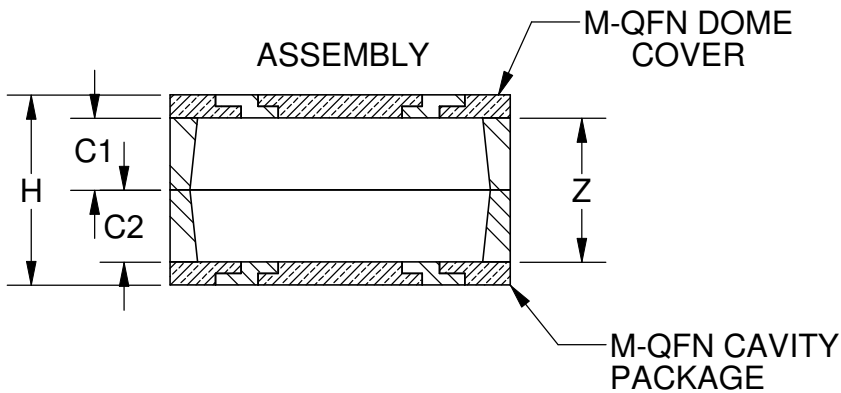
TOP VIEW



APPLICATION NOTES
USING M-QFN AS SHIELDED DOME LID ASSEMBLY



SECTION A-A



COMBINED PACKAGE DIMENSIONS				
	REF	DES	mm	MILS
I.D. INSIDE	Z	CAVITY	1.27	50
	C1	LID	0.635	25
	C2	QFN	0.635	25
O.D. OUTSIDE	A1	LID	0.81	32
	A	QFN	0.81	32
	H	TOTAL HEIGHT	1.62	64

LEAD FRAME: Cu (C-194F/H).
WALLS: SEMICONDUCTOR GRADE MOLD COMPOUND.

TOLERANCE UNLESS NOTED		APPROVALS		DATE						
X.X	+/- 0.3	DRAWN J. Hines		3/24/2011						
X.XX	+/- 0.03	ENG				TITLE M-QFN SHIELDED DOME LID APPLICATION NOTES				
X.XXX	+/- 0.003	MFG								
ANGLES +/- 0.5°		QA		SCALE 15:1		SIZE A		DRAWING NO. 200040		REV A
ALL DIMENSIONS IN		CUST		REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 1		
<input checked="" type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		THIRD ANGLE PROJECTION								